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**Paolo Bison
Douglas Burleigh**
Editors

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Contents

vii	<i>Authors</i>
ix	Conference Committees
xiii	<i>Introduction</i>

STANDARDS CERTIFICATIONS AND GUIDELINES

10214 02	A 2016 update on standards and guidelines relevant to thermographers [10214-2]
----------	---

FIRE ANALYSIS AND DETECTION

10214 04	Flame filtering and perimeter localization of wildfires using aerial thermal imagery [10214-4]
10214 05	Object localization in handheld thermal images for fireground understanding [10214-5]

ADDITIVE MANUFACTURING I

10214 07	Measurement of process dynamics through coaxially aligned high speed near-infrared imaging in laser powder bed fusion additive manufacturing [10214-7]
----------	---

ADDITIVE MANUFACTURING II

10214 08	Micro-scale thermal imaging of CO₂ absorption in the thermochemical energy storage of Li metal oxides at high temperature [10214-8]
10214 09	Thermal analysis of fused deposition modeling process using infrared thermography imaging and finite element modeling [10214-9]
10214 0A	Life cycle monitoring of lithium-ion polymer batteries using cost-effective thermal infrared sensors with applications for lifetime prediction [10214-10]

BIOLOGICAL AND MEDICAL APPLICATIONS

10214 0B	Thermographic image analysis for classification of ACL rupture disease, bone cancer, and feline hyperthyroid, with Gabor filters [10214-11]
10214 0D	Non-invasive characterization of normal and pathological tissues through dynamic infrared imaging in the hamster cheek pouch oral cancer model [10214-13]

- 10214 0E **About possibility of temperature trace observing on a human skin through clothes by using computer processing of IR image** [10214-14]
- 10214 0G **Pulse compression favourable aperiodic infrared imaging approach for non-destructive testing and evaluation of bio-materials** [10214-16]

NDT AND SIGNAL PROCESSING

- 10214 0H **Thermal inspection of a composite fuselage section using a fixed eigenvector principal component analysis method** [10214-17]
- 10214 0I **Numerical and experimental analyses for natural and non-natural impacted composites via thermographic inspection, ultrasonic C-scan and terahertz imaging** [10214-18]

VIBRO-THERMOGRAPHY AND THERMOMECHANICS

- 10214 0L **Characterizing open and non-uniform vertical heat sources: towards the identification of real vertical cracks in vibrothermography experiments** [10214-21]
- 10214 0M **Fatigue damage evaluation of short fiber CFRP based on phase information of thermoelastic temperature change** [10214-22]
- 10214 0N **Highly efficient ultrasonic vibrothermography for detecting impact damage in hybrid composites** [10214-23]
- 10214 0O **High-speed and high-definition infrared imaging for material characterization in experimental mechanics** [10214-24]
- 10214 0P **Non-destructive thermo-mechanical behavior assessment of glass-ceramics for dental applications** [10214-25]
- 10214 0Q **Energetic approach based on IRT to assess plastic behaviour in CT specimens (Best Student Paper Award)** [10214-26]

NDT AND MATERIAL EVALUATION

- 10214 0S **Thermographic investigations of metal inclusions in 3D printed samples** [10214-28]
- 10214 0T **Liquid nitrogen cooling in IR thermography applied to steel specimen** [10214-29]
- 10214 0U **Quantitative evaluation of water content in composite honeycomb structures by using one-sided IR thermography: is there any promise?** [10214-30]
- 10214 0W **Surface crack detection in different materials with inductive thermography** [10214-32]
- 10214 0X **Coating defect evaluation based on stimulated thermography** [10214-33]

MODELING HEAT CONDUCTION AND THERMOPHYSICAL PROPERTIES

- 10214 0Y **Application of the quadrupole method for simulation of passive thermography** [10214-35]
- 10214 0Z **Thermal diffusivity measurement of ring specimens by infrared thermography** [10214-37]
- 10214 10 **IR thermography for the assessment of the thermal conductivity of aluminum alloys**
[10214-38]
- 10214 11 **Analysis of pulse thermography using similarities between wave and diffusion propagation**
[10214-39]

BUILDINGS AND INFRASTRUCTURES

- 10214 12 **Infrared thermography applied to transport infrastructures monitoring: outcomes and perspectives (Best Paper Award)** [10214-40]
- 10214 13 **Infrared thermography applied to the study of heated and solar pavement: from numerical modeling to small scale laboratory experiments** [10214-41]

DETECTORS, IMAGING SYSTEMS AND CALIBRATION

- 10214 14 **Direct comparison of two pyrometers and a low-cost thermographic camera for time resolved LWIR temperature measurements** [10214-42]
- 10214 15 **Coaxial visible and FIR camera system with accurate geometric calibration** [10214-46]
- 10214 17 **Radiometric calibration of an ultra-compact microbolometer thermal imaging module**
[10214-44]
- 10214 18 **Investigation of the influence of spatial degrees of freedom on thermal infrared measurement** [10214-45]

POSTER SESSION

- 10214 1A **Thermography based prescreening software tool for veterinary clinics** [10214-49]
- 10214 1C **Thermal conductivity characterization of polyaniline doped material for thermoelectric applications** [10214-51]
- 10214 1E **Infrared image correction for the reduction of background reflection** [10214-53]
- 10214 1F **High-performance interfaces for the implementation of various cooled IR detectors**
[10214-54]
- 10214 1H **Modified algorithm for mineral identification in LWIR hyperspectral imagery** [10214-57]

- 10214 1I **Thermal NDT applying Candid Covariance-Free Incremental Principal Component Thermography (CCIPCT)** [10214-58]
- 10214 1J **Fatigue limit estimation of titanium alloy Ti-6Al-4V with infrared thermography** [10214-59]
- 10214 1K **The role of the continuous wavelet transform in mineral identification using hyperspectral imaging in the long-wave infrared by using SVM classifier** [10214-60]
- 10214 1L **Satellite image fusion by using a combination of IHS and HPM methods** [10214-61]

Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Abdulkadhim, Z., 0P	Kato, Yunitaka, 08
Akai, Atsushi, 1J	Kobayashi, C., 1E
Altenburg, Simon J., 14	Kordatos, E. Z., 0P
Alvandipour, Mehrdad, 0B, 1A	Krankenhagen, Rainer, 14
Ancona, Francesco, 0Q	Krauß, Matthias, 1F
Arora, Vanita, 0G	Lagueux, Philippe, 0O
Beaudoin, Georges, 1H, 1K	Lama, Norsang, 0B, 1A
Bison, P., 0T, 0Z, 10, 1C	Lane, Brandon M., 07
Blednov, Roman G., 0E	Laurie, Seth, 17
Boldrini, S., 1C	Le Touz, N., 13
Bolduc, Sean, 0H	Lei, Lei, 0T, 18
Bortolin, A., 0T, 0Z	Liaigre, K�vin, 1H, 1K
Cadelano, G., 0T, 0Z	L�pez de Uralde, P., 0L
Calliari, I., 10	Maldague, Xavier P. V., 0I, 0T, 18, 1H, 1I, 1K, 1L
Castelo, A., 0L	Malik, Anav, 0A
Celorio, R., 0L	Marcotte, Fr�d�rick, 0O
Chamberland, Martin, 1H, 1K	Marino, Dominic J., 0B, 1A
Chulkov, A. O., 0U	McIntosh, Gregory B., 02
Crini�re, A., 12	Mendioroz, A., 0L
Dahal, Rohini, 0B, 1A	Merci, Bart, 05
De Finis, Rosa, 0Q	Mishra, Deependra K., 0B, 1A
Derusova, D. A., 0N	Monti Hughes, Andrea, 0D
Djupkep Dizeu, Frank Billy, 18	Morikawa, Junko, 08
Druzhinin, N. V., 0N	Morton, Vince, 0O
Dua, Geetika, 0G	Moskovchenko, A. I., 0U
Dumoulin, J., 12, 13	Mulaveesala, Ravibabu, 0G
Famengo, A., 1C	Muniyappa, Amarnath, 0G
Farley, Vincent, 0O	Nakamura, Yu, 0M
Fernandes, Henrique, 0I	Nazarov, S., 10
Ferrarini, G., 0T, 0Z	Nekhoroshev, V. O., 0N
Feteira, A. M., 0P	Nonaka, Shinichi, 0M
Fleuret, Julien R., 0I, 18	Nugent, Paul W., 17
Fox, Jason C., 07	Ogasawara, N., 1E
Gagnon, Marc-Andr�, 0O	Ogino, Yuka, 15
Gali�tti, Umberto, 0Q, 0X	Okutomi, Masatoshi, 15
Genest, Marc, 0I	Oswald-Tranta, Beata, 0S, 0W
Gershenson, M., 11	Ouellet, Denis, 18
Gorosmendi, I., 0L	Padra, Claudio, 0D
Gorostegui-Colinas, E., 0L	Palumbo, Davide, 0Q, 0X
Gregory, Elizabeth D., 0Y	Pan, Y.-Y., 0U
Guyot, �ric, 0O	Pastor, Elsa, 04
Hamada, Kenichi, 0M	Perilli, Stefano, 0I
Harman, Rebecca, 0H	Planas, Eul�lia, 04
Herrera, Mar�a S., 0D	Riesland, David W., 17
Hsieh, Sheng-Jen, 09, 0A	Rios, Oriol, 04
Huff, Roy, 02	Rossi, S., 0Z, 10, 1C
Huot, Fran�ois, 1H, 1K	Sackman, Joseph, 0B, 1A
Ibarra-Castanedo, Clemente, 1H, 1I, 1K	Sakagami, Takahide, 0M, 1J
Jalalvand, Azarakhsh, 05	Salazar, A., 0L

Salva, Natalia, 0D
 Santa Cruz, Gustavo A., 0D
 Sarasini, Fabrizio, 0I, 0N
 Schmidt, Roland, 0S
 Schwint, Amanda, 0D
 Sfarra, Stefano, 0I, 0N, 18, 1I
 Shaw, Joseph A., 17
 Shestakov, Ivan L., 0E
 Shibata, Takashi, 15
 Shiozawa, Daiki, 0M, 1J
 Siddiqui, Juned A., 0G
 Sojasi, Saeed, 1H, 1K, 1L
 Takasu, Hiroki, 08
 Tamborrino, Rosanna, 0X
 Tanaka, Masayuki, 15
 Toullier, T., 13
 Trofimov, Vladislav V., 0E
 Trofimov, Vyacheslav A., 0E
 Tuschl, Christoph, 0S
 Umbaugh, David, 1A
 Umbaugh, Scott E., 0B, 1A
 Valero, Mario M., 04
 Vandecasteele, Florian, 04, 05
 Vavilov, V. P., 0N, 0U
 Verstockt, Steven, 04, 05
 Vettermann, Matthias, 1F
 Vollheim, Birgit, 1F
 Wachs, Marian, 1F
 Winfree, William P., 0Y
 Yamada, H., 1E
 Yeung, Ho, 07
 Yousefi, Bardia, 18, 1H, 1I, 1K
 Zalameda, Joseph N., 0H, 0Y
 Zamengo, Massimiliano, 08
 Zhang, Hai, 0I, 18
 Zhou, Xunfei, 09, 0A

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ThermoSense XXXIX
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Ralph B. Dinwiddie, Oak Ridge National Laboratory (United States)
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- 5 Additive Manufacturing II
Ralph B. Dinwiddie, Oak Ridge National Laboratory (United States)
Paolo Bison, Consiglio Nazionale delle Ricerche (Italy)
- 6 Biological and Medical Applications
Paolo Bison, Consiglio Nazionale delle Ricerche (Italy)
- 7 NDT and Signal Processing
Xavier P. V. Maldague, University Laval (Canada)
Joseph N. Zalameda, NASA Langley Research Center (United States)

- 8 Vibro-Thermography and Thermomechanics
Takahide Sakagami, Kobe University (Japan)
Arantza Mendioroz, Universidad del País Vasco (Spain)
- 9 NDT and Material Evaluation
Douglas Burleigh, La Jolla Cove Consulting (United States)
Paolo Bison, Consiglio Nazionale delle Ricerche (Italy)
- 10 Modeling Heat Conduction and Thermophysical Properties
Steven M. Shepard, Thermal Wave Imaging, Inc. (United States)
Paolo Bison, Consiglio Nazionale delle Ricerche (Italy)
- 11 Buildings and Infrastructures
Sheng-Jen Hsieh, Texas A&M University (United States)
- 12 Detectors, Imaging Systems and Calibration
Junko Morikawa, Tokyo Institute of Technology (Japan)
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Introduction

The Thermosense conference continues to play a significant role in assessing the state-of-the-art, current developments, and future trends in the applications of infrared thermography.

This year, for the first time, Thermosense was held in Anaheim, California (United States), on 9–13 April, 2017.

The international Thermosense community of academic scientists, industry professionals, and students submitted 62 abstracts and made 46 presentations. Countries represented this year included Argentina, Canada, India, Japan, Mexico, Russia, Tajikistan, and the United States, along with a contingent of researchers from European countries including Austria, Belgium, France, Germany, Italy, and the United Kingdom.

Two awards were presented for excellence in scientific achievement. The first award, for the best overall paper, involved the use of IR thermography in large scale applications: the study of buildings and infrastructures. The second was for the best student paper, which involved small/micro scale applications: the study of thermal/mechanical properties of materials.

The awards were sponsored by FLIR Systems Inc. and IRCameras LLC respectively. These two award-winning papers demonstrated the wide range of flexibility of infrared technology.

Other topics of growing interest represented at this year's Thermosense were the use of thermography in additive manufacturing, in biological and medical applications, and in the ever-growing application of nondestructive testing (NDT).

Thermosense promotes developments in infrared technology by hosting the annual "Vendor" session, which is now in its 13th year. This very popular session is a unique opportunity for people to learn about new equipment, systems, and accessories.

Next year the historic 40th (XL) Thermosense conference will be held in Orlando, Florida (United States) where most of our conferences have been. Many of our dedicated group have been coming to Thermosense for 20–30 years, and a small number attended Thermosense I.

We will plan some special events for Thermosense XL.

Paolo Bison
Douglas Burleigh